

The $\mu\text{-}Rwell$ technology for the IDEA detector

Federico Matias Melendi on behalf of the RD_FCC collaboration

University and INFN Ferrara - mlnfrc@unife.it

18-24 July 2024



OUTLINE

- FCC & IDEA introduction
- µ-RWELL technology and optimization
- μ -RWELL & TIGER integration



The FCC project

- The Future Circular Collider (FCC) study is developing designs for higher performance particle colliders that could follow on from the Large Hadron Collider (<u>LHC</u>).
- A new tunnel is planned with a circumference of 90.7 km, an average depth of 200 m and eight surface sites for up to four experiments.
- The tunnel would initially house the **FCC-ee**, an electron–positron collider for precision measurements. A second machine, the **FCC-hh**, would then be installed in the same tunnel, reusing the existing infrastructure



IDEA detector layout



IDEA innovative, cost-effective **concept**:

- <u>Silicon vertex detector</u>
- Short-drift, ultra-light <u>wire chamber</u>
- Dual-readout <u>calorimeter</u>
- Thin <u>solenoid</u> coil inside calorimeter system
- Muon system made of 3 layers of µRWELL detectors in the return yoke



The IDEA pre-shower

High resolution after of magnet to improve cluster reconstruction

Requirements:

- Efficiency > 98%
- Spatial Resolution < 100µm
- Total Area ~ 130m²

Detector layout:

- $50x50 \text{ cm}^2 \mu$ -RWELL with X-Y readout
- N° of channels ~ 1.3M
- Strip length 50cm



The idea muon detector

Reconstruction and Tag the muon

Requirements:

- Efficiency > 98%
- Spatial Resolution < 400µm
- Total Area ~ 1530m²

Detector layout:

- $50x50 \text{ cm}^2 \mu$ -RWELL detector with X-Y readout
- N° of channels ~ 5 M
- Strip length 50cm





µ-RWELL technology & optimization

µ-RWELL technology

The $\mu\text{-}\mathsf{RWELL}$ is a resistive MPGD, composed mainly of two elements:

- Cathode
- µ-RWELL PCB

The μ -RWELL PCB consists of:

- a WELL patterned kapton foil (with Cu-layer on top) acting as amplification stage
- a resistive DLC film with ρ ~ 50+100 M\Omega/ \Box
- a standard readout PCB with pad/strip segmentation

Well known performance on 10x10cm² prototypes:

- Efficiency > 98%
- Spatial resolution < 100µm
- Rate capability >> 10MHz/cm²





Test beam results 2021: 1D µ-RWELL

Configuration: 1D $\mu\text{-RWELL}$ coupled with APV25

Resistivity scan at fixed pitch

- Active area = 400x50 mm²
- Resistivity = 10-80 $M\Omega/\Box$
 - Strip pitch = 0.4 mm
 - Strip width = 0.15 mm



• Efficiency knee at 550 V, $\sigma x < 100 \ \mu m$



Test beam results 2022: 1D µ-RWELL

Configuration: 1D µ-RWELL coupled with APV25

Pitch scan at fixed resistivity

- Active area = 400x50 mm2
 - Resistivity = 30 $M\Omega/\Box$
- Strip pitch = 0.4-1.6 mm
- Strip width = 0.15 mm



TB2022 MUON µ-RWELL, Size

- Larger the strip pitch, lower the charge signal requiring a higher gain to reach full efficiency.
- Efficiency knee at 600 V, $\sigma x < 600 \mu m$ (for 0.8 mm pitch)

660 680 HV [V]

640

640

660

680

HV [V]

TB2022 MUON µ-RWELL, Charge

2D layouts possible for µ-RWELL









- Good perfomances ٠
- High gas gain, due to coupling of the X and Y strips
- Works at lower gas gain wrt the «COMPASS» readout

Charge transfer and charge sharing using capacitive coupling between a stack of layers or pads and the r/o.

- **Reduces the FEE channels** ٠
- Total charge is divided between X & Y r/o
- The TOP layout allows to work at lower gas gain wrt the "COMPASC" (X-Y r/o are decoupled)
- The X coordinate on the TOP of the . amplification stage induces same dead zone in the active area

2D layouts possible for μ -RWELL



- Good perfomances
- High gas required, due to coupling of the X and Y strips



Tested configurations

2D layouts possible for μ -RWELL





Test beam results 2023: 2D µ-Rwell

TOP r/o:

- The total charge isn't divided between X & Y
- Efficiency knee at ~ 500V
- Low efficiency plateau due to dead zone (~70%)
- Cluster Size does not change on X (TOP r/o), while changing on the Y (due to the DLC spread)
- Digital Spatial Resolution on the X

CS r/o:

- Efficiency knee at ~ 600V
- High efficiency plateau (~95%)
- Cluster size increases to 4 strips
 Charge sharing mechanism work
- Spatial resolution improves at higher gain reaching 150µm (with a strip pitch of 1.2mm)





1D µ-RWELL with TIGER/GEMROC DAQ -Testbeam July 2024 -



TIGER/GEMROC electronics

- TIGER/GEMROC DAQ has been developed for BESIII
 CGEM-IT
- It is a Modular and scalable system
- Designed for GEM detectors, but appropriate for similar MPGDs

The DAQ chain is based composed by:

- Front End Boards (FEBs), each FEB hosts 2 TIGERs
- Data and Low Voltage Patch Cards (DLVPC)
- GEM Read-Out Cards (GEMROC)



For more details: The CGEM-IT readout chain - A. Amoroso et al 2021 JINST 16 P08065

GEMROC electronics

Intel/ALTERA ARRIA V GX family FPGA development kit + interface card

The GEMROCs' tasks are:

- Distribute digital and analog voltage levels
- Configure the TIGERs
- Monitor currents and temperatures during operation
- Collect and organize output data from the TIGERs
- Receive trigger signal for trigger-matched operation



For more details: The CGEM-IT readout chain - A. Amoroso et al 2021 JINST 16 P08065

TIGER electronics

- First tests with a µ-RWELL 10x10cm² prototype
- Noise level very low (~1 fC)
- Input capacitance up to 100 pF
- TDC resolution < 50 ps
- Average gain ~ 10.75 mV/fc
- Maximum power consumption ~ 12mW/ch

For more details: The CGEM-IT readout chain - A. Amoroso et al 2021 JINST 16 P08065



Photo by M.Mignone



Distribution of thresholds of an entire chip (64 channels)

TEST BEAM SETUP

Detector under test features:

- Active area = 400x50 mm²
- Resistivity = 80 $M\Omega/\Box$
- Strip pitch = 0.4-1.6 mm
- Strip width = 0.15 mm
- 1D readout

Gas mixtures used:

- ArCO₂ (70:30)
- ArCO₂:CF₄(45:15:40)

Triple-GEM trackers used





Test beam data taking

- The data taking consisted of <u>HV scan</u>, <u>Drift scan</u> and <u>Thr. scan</u>, with both $Ar:CO_2$ and $Ar:CO_2:CF_4$
- The data anlysis is ongoing, and will be the task of the next months



SUMMARY



Thank you for your attention!



BACKUP SLIDES



IDEA muon system



Capacitive Sharing readout: Principle & Motivation

- Vertical stack of pad layers: charge transfer via capacitive coupling
- Pads have dedicated position from one layer to the layer underneath
- Doubling in size at each layer
- Transverse sharing of the charges between neighbouring pads of layer (i+1) from vertical charge transfer from layer (i)
- The scheme preserves spatial information i.e. the spatial resolution obtained with the largest readout strips or pads

Proof of concept established with 800 μm X-Y strips

Objective of the technology:

- Develop high performance and low channel count readout structures for MPGDs
- Reduce the number of readout electronic channels for large area MPGDs
- Low-cost technology for large area and standard PCB fabrication techniques



Goal: 50 µm for 1 mm strip r/o 150 µm for 1 cm2 pad r/o

Resistivity

[G.Bencivenni et al., "Performance of µ-RWELL detector vs resistivity of the resistive stage", NIM A 886 (2018) 36]



TIGER PARAMETERS

TIGER Parameters

- Input capacitance up to 100 pF
- Input dynamic range from 2 to 50 fC
- Noise on the Energy branch < 1800 e- ENC (0.29 fC)
- Jitter on the Time branch < 4 ns
- Thermal load 12.5 mW per channel
- Rate capability 60 kHz per channel

